

TOSHIBA LED LAMP GaP GREEN LIGHT EMISSION

**TLGD175**

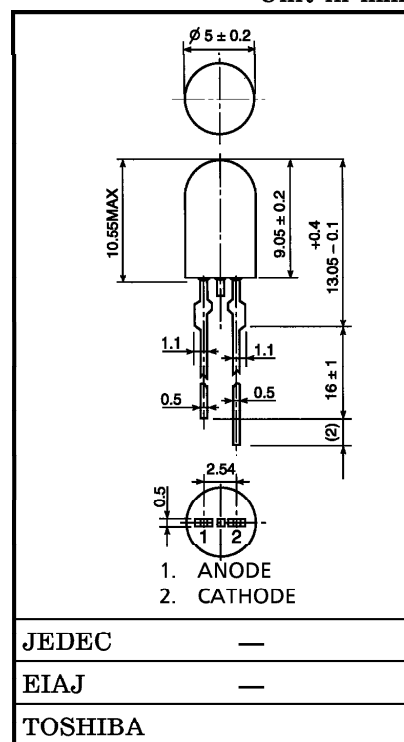
2 CHIP LED LAMP FOR MESSAGE BOARD

Unit in mm

- 2 Chip Series Connection
- All Plastic Mold Type : Clear Transparent Lens
- Low Drive Current, High Intensity Green Light Emission  
Recommended Forward Current :  $I_F = 15 \sim 20\text{mA}$  (DC)
- All Plastic Molded Lens, Provides an Excellent ON-OFF Contrast Ratio.
- Fast Response Time, Capable of Pulse Operation.
- Wide Radiation : Suitable for Message Board  
( $\pm 30\text{deg}$  : //,  $\pm 15\text{deg}$  :  $\perp$ )

MAXIMUM RATINGS ( $T_a = 25^\circ\text{C}$ )

CHARACTERISTIC	SYMBOL	RATING	UNIT
Forward Current (DC)	$I_F$	30	mA
Reverse Voltage	$V_R$	8	V
Power Dissipation	$P_D$	120	mW
Operating Temperature Range	$T_{opr}$	$-30 \sim 85$	$^\circ\text{C}$
Storage Temperature Range	$T_{stg}$	$-40 \sim 100$	$^\circ\text{C}$



JEDEC —

EIAJ —

TOSHIBA

Weight : 0.35g

ELECTRO-OPTICAL CHARACTERISTICS ( $T_a = 25^\circ\text{C}$ )

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Forward Voltage	$V_F$	$I_F = 20\text{mA}$	—	4.3	5.4	V
Reverse Current	$I_R$	$V_R = 8\text{V}$	—	—	5	$\mu\text{A}$
Luminous Intensity	$I_V$	$I_F = 20\text{mA}$ (Note)	153	400	—	mcd
			153	—	736	
Peak Emission Wave Length	$\lambda_p$	$I_F = 20\text{mA}$	—	567	—	nm
Spectral Line Half Width	$\Delta\lambda$	$I_F = 20\text{mA}$	—	25	—	nm

(Note) Rank selection carried out under next standard range respectively, although it needs  $\pm 15\%$  sdditionary for guaranteed limits.

P : 180-360mcd    Q : 320-640mcd

Each rank products is classified by package unit, and (PQ) includes P and Q.

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**PRECAUTION**

Please be careful of the followings.

- Soldering temperature : 260°C MAX.      Soldering time : 3s MAX.  
(Soldering portion of lead : below the lead stopper)
- If the lead is formed, the lead should be formed below the lead stopper without forming stress to the resin. Soldering should be performed after lead forming.

